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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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1N6638, 1N6639, 1N6640, 1N6641, 1N6642, 1N6643, 1N6638U & US, 1N6639U & US, 1N6640U & US, 1N6641U & US 1N6642U & US, 1N6643U & US



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Features

- Available in JAN, JANS, JANTX, JANTXV per MIL-PRF-19500/578 & /609
- · Switching Diodes
- · Non-Cavity Glass Plackage
- · Category I Metallurgically Bonded



Maximum Ratings

Operating Temperature: -65°C to +175°C Thermal Resistance:

Storage Temperature: -65°C to +175°C (R_{OJEC}): U & US 40 °C/W maximum at L = 0"

Operating Current: 300mA See Figure 6

Derating: See Figure 5 ($R_{\Theta JL}$): Leaded 150 °C/W maximum at L = .375"

Surge Current: $I_{FSM} = 2.5A$, half sine wave, See Figure 7

 $P_W = 8.3 \text{ms}$ Thermal Impedance: $(Z_{\Theta JX})$: 25 °C/W maximum

Electrical Specifications @ TA = +25 °C (Unless Otherwise Specified)

Types	V _{BR}	@ I _R	v_{WRM}	l	/ t _{fr} @ 200 mA	C _{T1} V _R =0 V	C _{T2} V _R =1.5 V	t_{rr} $I_R = 10mA$ $I_F = 10mA$	I_{R1} $V_{R}=V_{RWM}$ $T_{A}=150^{\circ}C$	I_{R2} $V_{R}=20V$ $T_{A}=150^{\circ}C$	I _{R3} V _R =20V	$V_{R} = V_{RWM}$
	V(pk)	μΑ	V(pk)	V _{FR} V(pk)	t _{fr} ns	pF	pF	ns	nA dc	nA dc	μA dc	μA dc
1N6638, U & US	150	100	125	5.0	20	2.5	2.0	4.5	35	500	50	100
1N6639, U & US	100	10	75	5.0	10	2.5	-	4.0	-	100	-	90
1N6640, U & US	75	10	50	5.0	10	2.5	-	4.0	-	100	-	90
1N6641, U & US	75	10	50	5.0	10	3.0	-	5.0	-	100	-	90
1N6642, U & US	100	100	75	5.0	20	5.0	2.8	5.0	25	500	50	100
1N6643, U & US	75	100	50	5.0	20	5.0	2.8	6.0	50	500	75	100

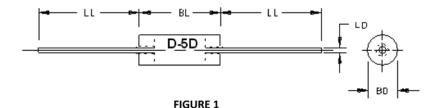
Types	٧ _F	@ I _F	V _{F2} @ I _F T _A = -55°C	l _F	
	V dc (min)	V dc (max)	V dc (max)	mA (pulsed)	
1N6638, U & US	-	1.1 0.8	1.2 -	200 10	
1N6639, U & US	-	1.2	1.3	500	
1N6640, U & US	0.54 0.76 0.82 0.87	0.62 0.86 0.92 1.0	- - - 1.1	1 50 100 200	
1N6641, U & US	-	1.1	1.2	200	
1N6642, U & US	-	0.8 1.2	- 1.2	10 100	
1N6643, U & US	-	0.8 1.2	- 1.4	10 100	



Revision Date: 2/5/2013



Outline Drawing



Symbol	Inc	hes	Millin	Notes	
	Min	Max	Min	Max	
BD	.056	.080	1.42	2.03	2
BL	.130	.180	3.30	4.57	
LD	.018	.022	.046	0.56	3
LL	1.00	1.50	25.40	38.10	

LEADED DESIGN DATA

CASE: D-5D, Hermetically sealed glass case, per MIL-PRF-19500/578 & /609

LEAD FINISH: Tin/Lead

LEAD MATERIAL: Copper clad steel **POLARITY:** Cathode end is banded.

PACKAGE WEIGHT: 0.150g

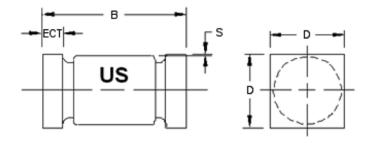


FIGURE 2

	Dimensions					
Symbol	Inc	hes	Millimeters			
	Min	Max	Min	Max		
D	.070	.085	1.78	2.16		
В	.165	.195	4.19	4.95		
ECT	.019	.028	.048	0.71		
S	.003		0.08			

U & US DESIGN DATA

CASE: D-5D, Hermetically sealed glass case, per MIL-PRF-19500/578 & /609

LEAD FINISH: Tin/Lead

END CAP MATERIAL (U, US): Copper **POLARITY:** Cathode end is banded.

PACKAGE WEIGHT: 0.095g

MOUNTING SURFACE SELECTION: The Axial Coefficient of Expansion (COE) of this device is approximately +4PPM/°C. The COE of the Mounting Surface System should be selected to provide a suitable match with this device.

NOTES:

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- 1. Dimensions are in inches. Millimeters are given for general information only.
- 2. Dimension BD shall be measured at the largest diameter.
- 3. The specified lead diameter applies in the zone between .050 inch (1.27 mm) from the diode body to the end of the lead. Outside of this zone lead shall not exceed BD.
- 4. In accordance with ASME V14.5M, diameters are equivalent to Φx symbology.
- 5. U-suffix parts are structurally identical to the US-suffix parts.



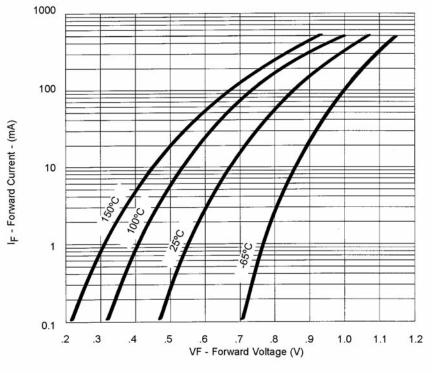


FIGURE 3
Typical Forward Current vs
Forward Voltage

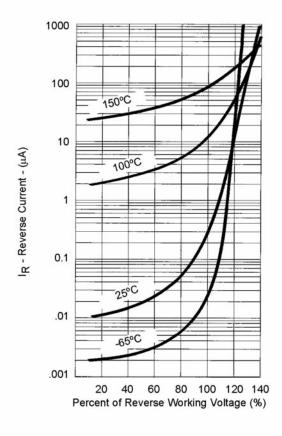
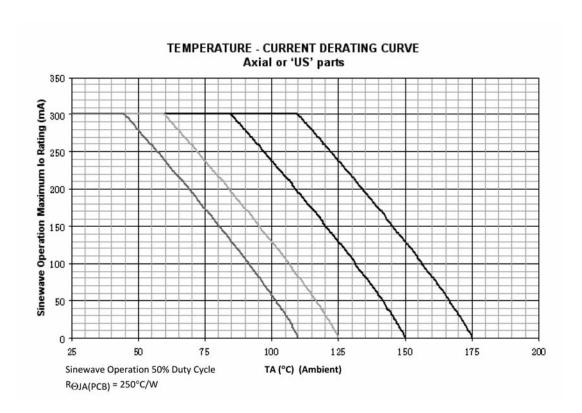


FIGURE 4
Typical Reverse Current vs
Reverse Voltage

Note:

All temperatures shown on graphs are junction temperatures





NOTES:

- 1. All devices are capable of operating at ≤ TJ specified on this curve. Any parallel line to this curve will intersect the appropriate current for the desired maximum TJ allowed.
- 2. Derate design curve constrained by the maximum junction temperatures and current rating specified. (See 1.3.)
- 3. Derate design curve chosen at TJ ≤ 150°C, where the maximum temperature of electrical test is performed.
- 4. Derate design curves chosen at TJ ≤ 125°C, and 110°C to show current rating where most users want to limit TJ intheir application.



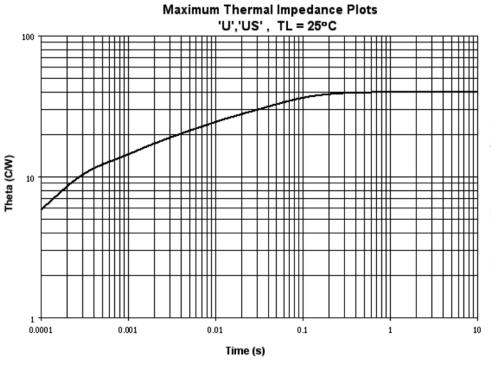


FIGURE 6. <u>Thermal impedance – all U and US devices</u>.

 $R_{\Theta JL} = 40^{\circ} C/W$

 $Z_{\Theta JX} = 25^{\circ}C/W$ maximum at $t_H = 10$ ms

Lead spacing = .375 inch mounted to an infinite heat dissipater

FIGURE 7. Thermal impedance (axial leads).

 $R_{\Theta JL}$ = 150°C/W

 $Z_{\Theta JX} = 25^{\circ}C/W$ maximum at $t_H = 10$ ms

Lead spacing = 0 inch mounted to an infinite heat dissipater



Suggested Minimum Footprints D-5D (D-BODY) U, US DIODES

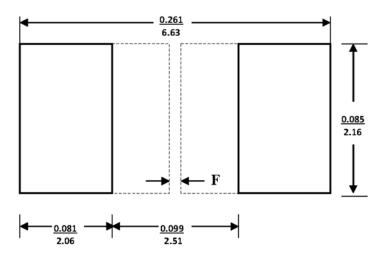


FIGURE 8

NOTES:

- 1. Dimensions are in inches / mm.
- 2. The dimensions listed will match the device terminals based on worst-case package outline drawings and assuming accuracy of device placements is within 0.005 inches. Footprints also provide for solder filets at the outer ends of the device at least as wide as the terminals.
- 3. F designates recommendation to fill unused area with an extended copper pad in order to reduce the CTE difference between the device and the PC board. The extended area may be3 coated with a solder mask, the width of F depends upon your PCB design rules.

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Our passion for performance is defined by three attributes represented by these three icons: solution-minded, performance-driven and customer-focused.

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